COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

HEAT SINK FOR CHIP PACKAGE AND BONDING METHOD THEREOF

the specif	ication of whic	h				
	tached hereto.					
	filed on	ial Na		and was amanded an		
as A	pplication Ser	iai ino	and was amended on		·	
specificati I acl applicatio I her applicatio foreign ap	on, including to knowledge the in accordance by claim fore n(s) for patent priority is claim for patent priority is claim	he claims, as amended to duty to disclose inforce with Title 37, Code or ign priority benefits und tor inventor's certificatent or inventor's certined:	nd understand the content by any amendment referred mation which is material to f Federal Regulations, § 1. der Title 35, United States Cate listed below and have ficate having a filing date be	ed to above. the patenta 56(a). Code, § 119 also identific	ability of this of any foreign ed below any	
Prior Fore	ign Application	n(s):				
	Number	Country	Date Filed(yyyy/mm/dd)	Yes	No	
9	1137108	Taiwan, R.O.C.	2002/12/24	X		
) and/or agent(s) to prosec ark Office connected therev		ication and to	
	la Lee i Huang es C.H. Wu	(Reg. No. 46,863 (Reg. No. 43,330 (Reg. No. 39,081))	(Reg. No.	53,226)	
SEND	CORRESPON	NDENCE TO:		DIRECT TELEPHONE CALLS TO: (Name and telephone number)		
JIANQ CHYUN Intellectual Property Office 7F1, No. 100, Roosevelt Rd., Sec. 2, Taipei 100, Taiwan, R.O.C. TEL: 886-2-2369 2800 FAX: 886-2-2369 7233				da Lee		

COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature:

Sole or First Joint Inventor: Sung-Fei Wang

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address: 1F., No. 21, Alley 90, Lane 729, Chia-Chang, Nan-Tzu District,

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Date:_